



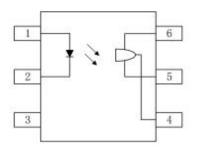
Photo Coupler Product Specification

HT-H11LX



■ Package





Pin Configuration

- 1. Anode
- 2. Cathode
- 3. No Connection
- 4. VO
- 5. GND
- 6. VCC

■ Description

The HT-H11LX series of devices each consist of a GaAs infrared emitting diode optically coupled a high speed integrated circuit detector. The output detector incorporates a Schmitt trigger, which provides hysteresis for noise immunity and pulse shaping.

The devices are in a 6-pin DIP package and available in wide-lead spacing and SMD option.

■ Features

- High data rate, 1MHz typical (NRZ)
- Free from latch up and oscillation throughout voltage and temperature ranges
- Microprocessor compatible drive
- Logic compatible output sinks 16mAat 0.4V maximum
- Guaranteed on/off threshold hysteresis
- Wide supply voltage capability, compatible with all popular logic systems
- High isolation voltage between input and output (Viso=5000 V rms)
- Compact dual-in-line package
- The product itself will remain within RoHS compliant version
- UL approved
- VDE approved
- CQC approved



■ Applications

- Logic to logic isolator
- Programmable current level sensor
- Line receiver—eliminate noise and transient problems
- AC to TTL conversion—square wave shaping
- Digital programming of power supplies Interfaces computers with peripherals



■ Product Nomenclature

The product name is designated as below:

<u>HT</u> - <u>H11LX</u> - <u>X</u> <u>X</u> - <u>X</u> <u>X</u> - <u>X</u> <u>X</u>

1 2 3 4 5

Designation:

HT =Hengtuo Technology Co.,LTD.

H11LX= Product Series (X: 1, 2, 3)

- ① = Lead form option(S1,M,NONE)(1)
- ② = Tape and Reel option(TA,TA1,NONE)(2)
- ③ = VDE order option(fixed code "V")
- ④ = Halogen free option(fixed code"G")
- ⑤ = Customer code

Notes

1.Lead form option:

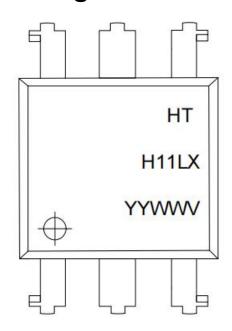
Symbol	Description
S1	DIP6-S1
М	DIP6-M
NONE	DIP6 Normal

2.Tape and Reel option:

Symbol	Description
TA&TA1	Tape and Reel Type
NONE	DIP Type



Marking Information



Designation:

HT denotes Hengtuo 30XX denotes Device YY denotes year code WW denotes week code

V denotes VDE

■ Maximum Ratings

Parameter		Symbol	Values	Unit
	Forward Current	I _F	50	mA
Innut	Reverse Voltage	V_R	6	V
Input	Power Dissipation	Р	120	MW
	Junction Temperature	Tj	125	$^{\circ}$
Output	V45 Allowed Range	Vo	0 to 16	V
	V65 Allowed Range	VCC	3 to 16	V
	Output Current	lo	50	mA
	Power dissipation	PD	150	mW
Total power dissipation		Ptot	250	mW
Isolation voltage (1)		Viso	5000	V rms
Operating temperature		Topr	-55~+100	°C
Storage temperature		Tstg	-55~+125	°C
Soldering temperature (2)		Tsol	260	°C

Notes:

- (1) AC for 1 minute, R.H.= $40 \sim 60\%$ R.H. In this test, pins 1, 2 & 3 are shorted together, and pins 4, 5 & 6 are shorted together.
- (2) For 10 seconds



■ Electronic Optical Characteristics (TA = 25°C)

	Paramet	er	Symbol	Min.	Тур.	Max.	Unit	Conditon
loout	Forward V	Forward Voltage		-	1.2	1.4	V	I _F =20mA
Input	Reverse C	urrent	I _R	-	-	5	μA	V _R =6V
	Operation Range	Voltage	Vcc	3	-	15	V	>
Output	Supply Cu	rrent	ICC(off)	1	1.6	5	V	I _F =0mA, Vcc=5V
Catpat	Output Cu	rrent, High	Іон	ı	-	100uA	V/μs	IF=0mA, V _{CC} =Vo=15V
	Isolation R	tesistance	R _{ISO}	10 ¹¹	-	_	Ω	V _{I-O} =500VDC
	Supply Current		ICC(on)		1.6	5	mA	I _F =10mA, V _{CC} =5V
	Output Voltage .low		V _{OL}		-	0.4	V	V_{CC} =5V, I_F = IFon(max.), R_L =270 Ω
	Threshold Current 1	HT-H11L1		-	-	1.6	mA	V _{CC} =5V, R _L =270 Ω
		HT-H11L2	IFon	-	-	10		
Transfer		HT-H11L3		-	-	5		
Charact eristics	Turn off Threshold Current		IFoff	0.5	-	0.9	mA	V_{CC} =5 V , R_L =270 Ω
	Hysteresis Ratio		IFoff /IFon	ı	-	4	mA	V_{CC} =5 V , R_L =270 Ω
	Turn on Time		ton	-	-	4	uS	
	Fall Time	Fall Time		-	0.1	-	uS	Vcc=5V,
	Turn off Time		toff	-	-	4	uS	I_F =IFon, R _L =270 Ω
	Rise Time		tr	-	0.1	-	uS	
	Data Rate			-	1	-	MHz	



Characteristics Curves

Fig.1 Forward current vs Ambient temperature

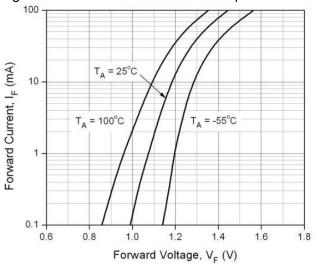


Fig.3 Turn on threshold current vs Supply voltage

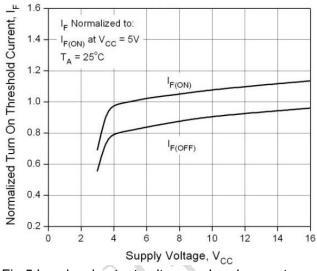


Fig.5 Low level output voltage vs Load current

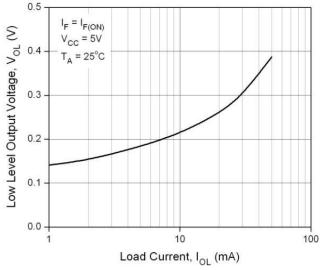


Fig.2 Transfer characteristics

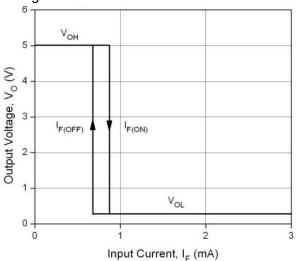


Fig.4 Turn on threshold current vs Ambient temperature

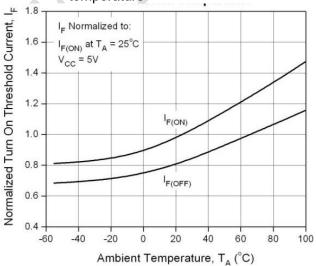


Fig.6 Supply current vs Supply voltage

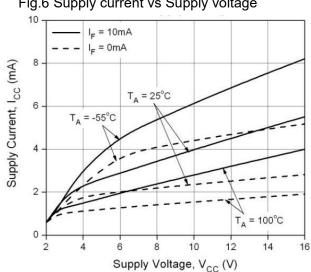
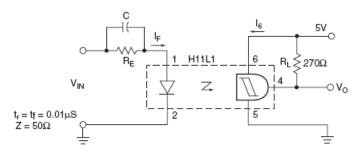
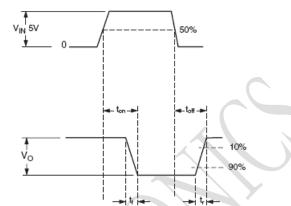




Fig.7 Switching time test circuit & Wave forms

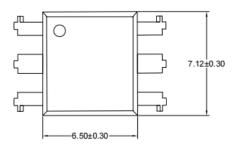


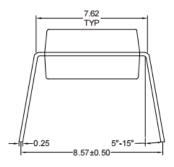


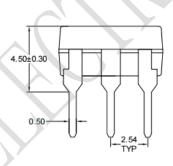


■ Outline Dimension

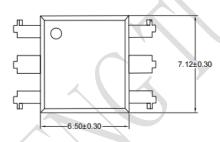
DIP Normal Type:

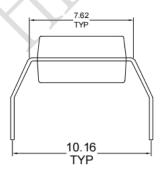


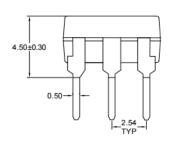




DIP M Type:

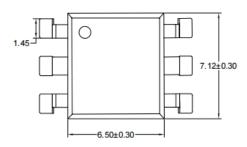


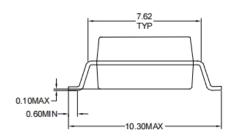


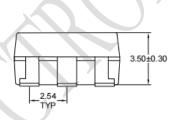




SMD S1 Type:





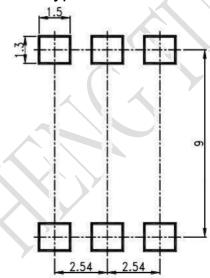


Unit: mm

Tolerance: ±0.1mm

■ Recommended solder pad Design

For S1 type:



Unit: mm

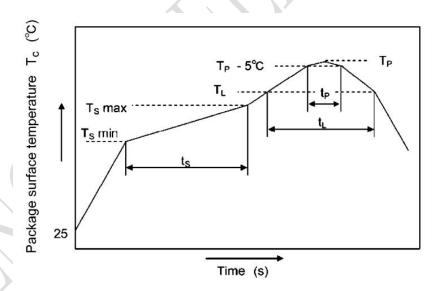
Tolerance: ±0.1mm



■ Temperature Profile Of Soldering

1. IR Reflow soldering (JEDEC-STD-020D compliant)

Profile item	Conditon
Preheat	
-Temperature Min (TSmin)	150°C
-Temperature Max (TSmax)	200°C
-Time (min to max) (ts)	90±30 sec
Soldering zone	
-Temperature (TL)	217°C
-Time (t∟)	60-150 sec
Peak Temperature (TP)	260°C
-Time (TP-5℃to TP) (ts)	30 sec
Ramp-up rate	3°C / sec max
Ramp-down rate	3~6°C/ sec



Notes:

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.



2. Wave soldering (JEDEC22A111 compliant)

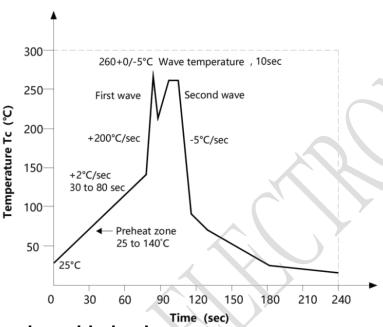
One time soldering is recommended within the condition.

Temperature:260+0/-5°C.

Time:10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



3. Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

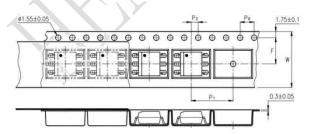
Temperature: 380+0/-5°C

Time: 3 sec max.

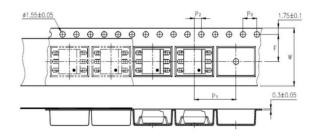
■ Packing

1. Tape and Reel

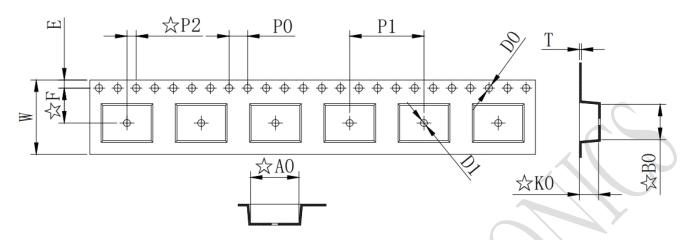
Option TA1:



Option TA:







Deminsion/mm	W	E	F	P0	P1	P2
Packagetype:S	16±0.2	1.75±0.1	7.5±0.1	4±0.1	16±0.1	2±0.1

Deminsion/mm	A0	B0	D0	D1	K0
Packagetype:S	10.45±0.1	7.6±0.1	1.5±0.1	1.5±0.1	4.1±0.1

1.Reel

Packagetype:S	Reel	Inner carton	Outer carton
QTY/PCS	1K/reel	2K(2 reels)	20K

2. Tape and Tube

Package type:Normal&M	Tube	Outer carton
QTY/PCS	65	3.25K(50 tubes)



■ Attention:

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